

INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Not for submission under 37 CFR 1.99)	Application Number		10531611
	Filing Date		2005-11-04
	First Named Inventor	Boon Chew Ng	
	Art Unit	1793	
	Examiner Name	Megha S. Mehta	
	Attorney Docket Number	117843.00002	

U.S.PATENTS

Examiner Initial*	Cite No	Patent Number	Kind Code ¹	Issue Date	Name of Patentee or Applicant of cited Document	Pages, Columns, Lines where Relevant Passages or Relevant Figures Appear
	1	6390351		2002-05-21	Kasai, et al.	

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	1	2001-156434	JP		2001-06-08	Hitachi Via Mechanics Ltd.		<input type="checkbox"/>

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1	"BGA Baller", New Products Section, Circuits Assembly magazine, page 76, July, 1999.	<input type="checkbox"/>
2	"BGA Reballing", SMT magazine, page 67, February, 2000.	<input type="checkbox"/>
3	"Patent to Vanguard for BGA Sphere-Attach Process", Briefs section, SMT magazine, September, 1996.	<input type="checkbox"/>
4	Advanced Packaging article. "Void-free, flux-free process for placement and attach of solder balls." February, 2000.	<input type="checkbox"/>

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